

**Intel Patent Sales –**

**IAM Lot 18 (Packaging – Architecture)**

**Lot 18 Description:** Lot 18 includes 20 patent assets. The patents in Lot 18 relate to various architecture technologies for IC packaging, including low profile packages with enclosed power supplies, stacked microelectronic packages, and wireless connections for IC packages. The patents also relate to package interconnects with thermoelectric coolers. [Uploaded 30 January 2017.]

	<b>Patent #</b>	<b>Granted or Pending</b>	<b>Country Code</b>	<b>Title</b>
1.	6812566	Granted	US	LOWER PROFILE PACKAGE WITH POWER SUPPLY IN PACKAGE
2.	100353545	Granted	CN	LOWER PROFILE PACKAGE WITH POWER SUPPLY IN PACKAGE
3.	10-0611865	Granted	KR	LOWER PROFILE PACKAGE WITH POWER SUPPLY IN PACKAGE
4.	575952	Granted	TW	LOWER PROFILE PACKAGE WITH POWER SUPPLY IN PACKAGE
5.	6600222	Granted	US	STACKED MICROELECTRONIC PACKAGES
6.	1669140	Granted	CN	STACKED MICROELECTRONIC PACKAGES
7.	1080992	Granted	HK	STACKED MICROELECTRONIC PACKAGES
8.	10-0667145	Granted	KR	STACKED MICROELECTRONIC PACKAGES
9.	43010	Granted	TH	STACKED MICROELECTRONIC PACKAGES
10.	8084867	Granted	US	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
11.	8513108	Granted	US	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES

	Patent #	Granted or Pending	Country Code	Title
12.	8981573	Granted	US	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
13.	8963333	Granted	US	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
14.	9385094	Granted	US	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
15.	101449375	Granted	CN	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
16.	10-1043484	Granted	KR	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
17.	146844	Granted	SG	APPARATUS, SYSTEM, AND METHOD FOR WIRELESS CONNECTION IN INTEGRATED CIRCUIT PACKAGES
18.	7851905	Granted	US	MICROELECTRONIC PACKAGE AND METHOD OF COOLING AN INTERCONNECT FEATURE IN SAME
19.	101399240	Granted	CN	MICROELECTRONIC PACKAGE AND METHOD OF COOLING AN INTERCONNECT FEATURE IN SAME
20.	10-1026618	Granted	KR	MICROELECTRONIC PACKAGE AND METHOD OF COOLING AN INTERCONNECT FEATURE IN SAME